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(54) Title: WIRE BONDING METHODS AND BONDING FORCE CALIBRATION

(57) Abstract: A method of applying bonding energy to form a bond between a portion of a wire and a contact of a bonding location using a wire bonding machine is provided. The method includes: (1) moving a bonding tool towards the contact; (2) detecting when a portion of the contact (100a) is pressed against a device supporting surface (112) of the wire bonding machine; and (3) applying bonding energy to the portion of the contact such that a bond is formed between the contact and the portion of wire.

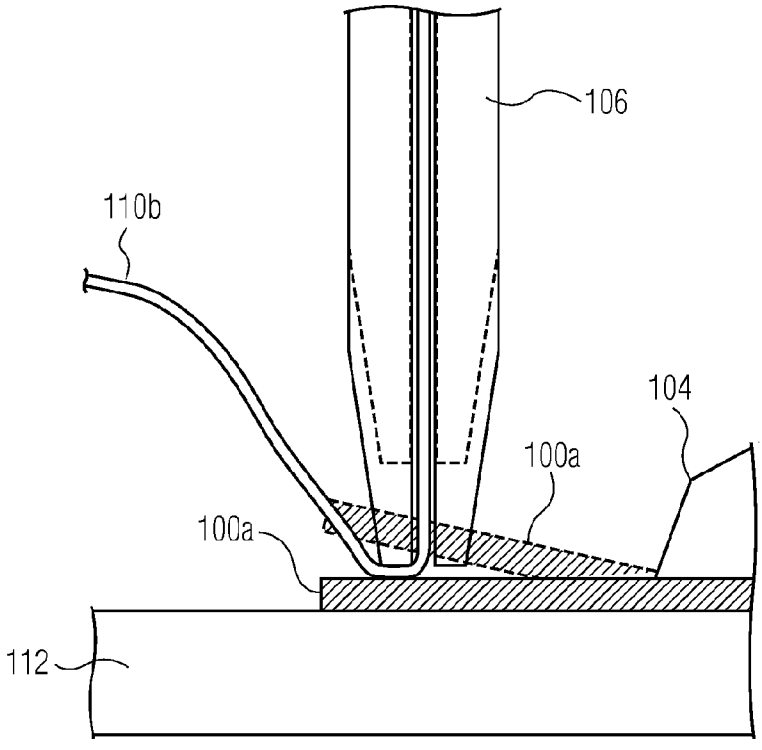


FIG. 1B

WO 2008/140541 A1

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